

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior claims, and listings of claims, in the application:

Listing of Claims

Claim 1 (Previously Presented): A semiconductor light-emitting element mounting member comprising:

a substrate; and

a metal film formed on a surface of said substrate, formed from Ag, Al, or an alloy containing said metals, and functioning as an electrode layer for mounting at least one of a semiconductor light-emitting element and a reflective layer for reflecting light from a semiconductor light-emitting element;

wherein the thickness of the metal film is 0.5 - 3 μm and crystal grains of said metal or alloy forming said metal film have a particle diameter along a surface plane of said metal film is no more than 0.5 μm and said surface of said metal film has a center-line average roughness Ra of no more than 0.1 μm .

Claim 2 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein an adhesion layer and a barrier layer are formed, in sequence, on said substrate, with said metal film being formed on said barrier layer.

Claim 3 (Previously Presented): A semiconductor light-emitting element mounting member according to claim 1 wherein said metal film is formed as an alloy of at least one of Ag and Al and

other metal, a proportional content of said other metal being 0.001 - 10 percent by weight.

Claim 4 (Original): A semiconductor light-emitting element mounting member according to claim 3 wherein said other metal is at least one type of metal selected from a group consisting of Cu, Mg, Si, Mn, Ti, and Cr.

Claim 5 (Canceled).

Claim 6 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein said metal film is formed from Al alone or from an alloy of Al and other metal.

Claim 7 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein a thermal expansion coefficient of said substrate is $1 \times 10^{-6}/K$ - $10 \times 10^{-6}/K$.

Claim 8 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein a thermal conductivity of said substrate is at least 80 W/mK.

Claim 9 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein said semiconductor light-emitting element mounting member is a flat submount.

Claim 10 (Previously presented): A semiconductor light-emitting element mounting member

of claim 1 further comprising a semiconductor light-emitting element mounted thereto.

Claim 11 (Previously presented): A semiconductor light-emitting device according to claim 10 wherein the output of said semiconductor light-emitting element is at least 1 W.

Claim 12 (new): A semiconductor light-emitting device according to claim 1 wherein said substrate is an insulative ceramic.

Claim 13 (new): A semiconductor light-emitting device according to claim 12 wherein the insulative ceramic is selected from a group consisting of AlN, Al₂O₃, SiC, Si₃N₄, BeO, BN, and insulative Si.